

STRUCTURE Silicon monolithic integrated circuit

PRODUCT NAME BU9796FS

FUNCTION LCD control driver for segment type LCD display

FEATURE O LCD drive output : Common output : 4, Segment output : 20

O built-in Display Data RAM(DDRAM): 20*4=80bit

O 2-wire Serial Interface (SCL, SDA)

O built-in Oscillator circuit

O built-in LCD Voltage Generator circuit: 1/2, 1/3Bias, 1/4Duty, Buffer AMP

O No external component

O Low power consumption design

O support standby mode

O operating power supply: 2.5V ~ 5.5V

\bigcirc Absolute maximum ratings (VSS = 0V)

Parameter	Symbol	Rated values	Unit	Remarks
Power supply voltage 1	VDD	-0.5 ~ +7.0	V	Power supply
Power supply voltage 2	VLCD	-0.5 ~ VDD	V	LCD drive voltage
Allowable loss	Pd	0.64*1	W	
Input voltage range	VIN	-0.5 ~ VDD+0.5	V	
Operational temperature range	Topr	-40 ~ +85	°C	
Storage temperature range	Tstg	-55 ∼ +125	°C	

^{*1} When use more than Ta=25°C, subtract 6.4mW per degree.

\bigcirc Recommend operating conditions (Ta = 25°C, VSS = 0V)

Parameter	Symbol	MIN	TYP	MAX	Unit	Remarks
Power supply voltage 1	VDD	2.5	-	5.5	V	Power supply
Power supply voltage 2	VLCD	0	-	VDD-2.4	V	LCD drive voltage

Note: Please use in VDD-VLCD ≥ 2.5V condition.

- This product is not designed against radioactive ray.
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Status of this document

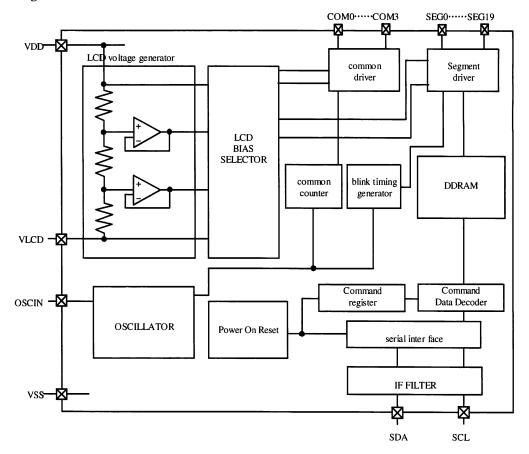
The Japanese version of this document is the formal specification.

A customer may use this translation version only for a reference to help reading the formal version.

If there are any differences in translation version of this document, formal version takes priority.



O Block diagrams



O Electrical Characteristics

DC Characteristics (VDD=2.5~5.5V, VSS=0V, Ta=-40~85°C; unless otherwise specified)

Parameter		Symbol		Limit		Unit	Condition
		Symbol	MIN	TYP	MAX	Oiiit	Condition
"H" level input voltage		VIH	0.7VDD	-	VDD	V	
"L" level input voltage	-	VIL	VSS	-	0.3VDD	V	
"H" level input current		IIH	-	-	1	uA	
"L" level input current		IIL	-1	-	-	uA	
LCD Driver on resistance	SEG	RON	-	3	-	kΩ	Iload=±10uA
LCD Driver on resistance	COM	RON	•	3	-	kΩ	Hoad=± IouA
VLCD supply voltage		VLCD	0	<u>-</u>	VDD -2.4	V	VDD-VLCD≧2.5V
Standby current 1		IDD1	-	_	5	uA	Display off, Oscillation off
Operating current		IDD2	-	12.5	30	uA	VDD=3.3[V], Ta=25, Power save mode SR = Power save mode I, Power save mode FR = Power save mode I, 1/3 bias, Frame inversion



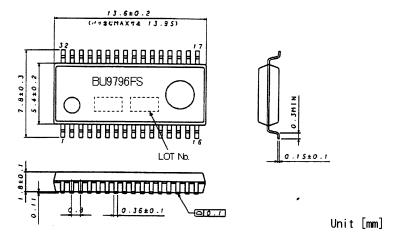
Oscillation Characteristics (Ta=-40~85°C, VDD=2.5~5.5V, VSS=0V)

Parameter	Symbol		Limit		Unit	Condition	
Tarameter	Symbol	MIN	TYP	MAX	Unit	Condition	
Frame frequency	fCLK	56	80	104	Hz	Power save mode FR = Normal mode	

MPU interface Characteristics (Ta=-40~85°C, VDD=2.5V~5.5V, VSS=0V)

Parameter	Symbol		Limit		Unit	Condition
	Symbol	MIN	TYP	MAX	Om	Condition
Input rise time	tr	-	-	0.3	us	
Input fall time	tf	-		0.3	us	
SCL cycle time	tCYC	2.5	-	-	us	
"H" level SCL pulse width	tHW	0.6	-	-	us	
"L" level SCL pulse width	tLW	1.3	-	-	us	
SDA setup time	tSDS	100	•	-	ns	
SDA hold time	tSDH	100	-	-	ns	
Bus free time	tBUF	1.3	-	•	us	
START condition hold time	tHD;STA	0.6	-	-	us	
START condition setup time	tSU;STA	0.6	-	-	us	
STOP condition setup time	tSU:STO	0.6	-	-	us	

Outline drawing



Package: SSOP-A32

O Terminal number/name

1	SEG2		CEC10	17	CEC10	ΩE	V00
ı	SEGZ	9	SEG10	17	SEG18	25	VSS
2	SEG3	10	SEG11	18	SEG19	26	TEST1
3	SEG4	11	SEG12	19	COMO	27	TEST2
4	SEG5	12	SEG13	20	COM1	28	OSCIN
5	SEG6	13	SEG14	21	COM2	29	SCL
6	SEG7	14	SEG15	22	COM3	30	SDA
7	SEG8	15	SEG16	23	VLCD	31	SEG0
8	SEG9	16	SEG17	24	VDD	32	SEG1



Cautions on use

(1) Absolute Maximum Ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down devices, thus making impossible to identify breaking mode such as a short circuit or an open circuit. If any special mode exceeding the absolute maximum ratings is assumed, consideration should be given to take physical safety measures including the use of fuses, etc.

(2) Operating conditions

These conditions represent a range within which characteristics can be provided approximately as expected. The electrical characteristics are guaranteed under the conditions of each parameter.

(3) Reverse connection of power supply connector

The reverse connection of power supply connector can break down ICs. Take protective measures against the breakdown due to the reverse connection, such as mounting an external diode between the power supply and the IC's power supply terminal.

(4) Power supply line

Design PCB pattern to provide low impedance for the wiring between the power supply and the GND lines. In this regard, or the digital block power supply and the analog block power supply, even though these power supplies has the same level of potential, separate the power supply pattern for the digital block from that for the analog block, thus suppressing the diffraction of digital noises to the analog block power supply resulting from impedance common to the wiring patterns. For the GND line, give consideration to design the patterns in a similar manner.

Furthermore, for all power supply terminals to ICs, mount a capacitor between the power supply and the GND terminal. At the same time, in order to use an electrolytic capacitor, thoroughly check to be sure the characteristics of the capacitor to be used present no problem including the occurrence of capacity dropout at a low temperature, thus determining the constant.

(5) GND voltage

Make setting of the potential of the GND terminal so that it will be maintained at the minimum in any operating state. Furthermore, check to be sure no terminals are at a potential lower than the GND voltage including an actual electric transient.

(6) Short circuit between terminals and erroneous mounting

In order to mount ICs on a set PCB, pay thorough attention to the direction and offset of the ICs. Erroneous mounting can break down the ICs. Furthermore, if a short circuit occurs due to foreign matters entering between terminals or between the terminal and the power supply or the GND terminal, the ICs can break down.

(7) Operation in strong electromagnetic field

Be noted that using ICs in the strong electromagnetic field can malfunction them.

(8) Inspection with set PCB

On the inspection with the set PCB, if a capacitor is connected to a low-impedance IC terminal, the IC can suffer stress. Therefore, be sure to discharge from the set PCB by each process. Furthermore, in order to mount or dismount the set PCB to/from the jig for the inspection process, be sure to turn OFF the power supply and then mount the set PCB to the jig. After the completion of the inspection, be sure to turn OFF the power supply and then dismount it from the jig. In addition, for protection against static electricity, establish a ground for the assembly process and pay thorough attention to the transportation and the storage of the set PCB.

(9) Input terminals

In terms of the construction of IC, parasitic elements are inevitably formed in relation to potential. The operation of the parasitic element can cause interference with circuit operation, thus resulting in a malfunction and then breakdown of the input terminal. Therefore, pay thorough attention not to handle the input terminals, such as to apply to the input terminals a voltage lower than the GND respectively, so that any parasitic element will operate. Furthermore, do not apply a voltage to the input terminals when no power supply voltage is applied to the IC. In addition, even if the power supply voltage is applied, apply to the input terminals a voltage lower than the power supply voltage or within the guaranteed value of electrical characteristics.

(10) Ground wiring pattern

If small-signal GND and large-current GND are provided, It will be recommended to separate the large-current GND pattern from the small-signal GND pattern and establish a single ground at the reference point of the set PCB so that resistance to the wiring pattern and voltage fluctuations due to a large current will cause no fluctuations in voltages of the small-signal GND. Pay attention not to cause fluctuations in the GND wiring pattern of external parts as well.

(11) External capacitor

In order to use a ceramic capacitor as the external capacitor, determine the constant with consideration given to a degradation in the nominal capacitance due to DC bias and changes in the capacitance due to temperature, etc.

(12) No Connecting input terminals

In terms of extremely high impedance of CMOS gate, to open the input terminals causes unstable state. And unstable state brings the inside gate voltage of p-channel or n-channel transistor into active. As a result, battery current may increase. And unstable state can also causes unexpected operation of IC. So unless otherwise specified, input terminals not being used should be connected to the power supply or GND line.

(13) Rush current

When power is first supplied to the CMOS IC, it is possible that the internal logic may be unstable and rush current may flow instantaneously. Therefore, give special condition to power coupling capacitance, power wiring, width of GND wiring, and routing of connections.

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Appendix1-Rev2.0